2.4GHz Chip Antenna: SURL502006T79

Application:

WLAN, 802.11b/g, Bluetooth, etc...

Features

SMD, high reliability, ultra Impact, Omni-directional...

Part number

(5) Frequency

SURL	502006	T79	R	245	
(1)	(2)	(3)	(4)	(5)	
(1)Product Model			SURL		
(2) Size Code			5.0x2	.0x0.6mm	
(3) Type Code			T79		
(4) Pac	(4) Packing			Tape and reel	

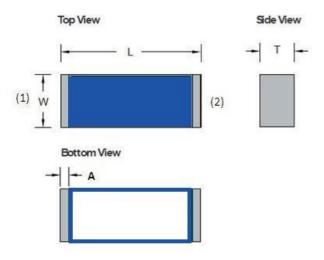
Electrical Specification

2400 ~2484 MHz	
3.5dBi (Typ.)	
50 Ohm	
10 dB (Min)	
Linear	
Omni-directional	
-40 ~85°C	

2.45GHz

The specification is defined on EVB.

Dimension and Terminal Configuration



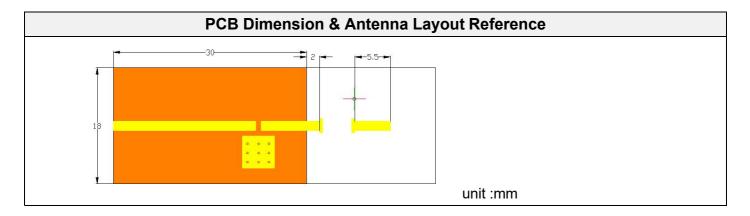
Dimension (mm)				
L	5.0 +-0.20		No.	
W	2.0+- 0.20		1	
Т	0.60+-0.20		2	
Α	0.20+-0.20			
	FootPrint	(Un	it : mm)

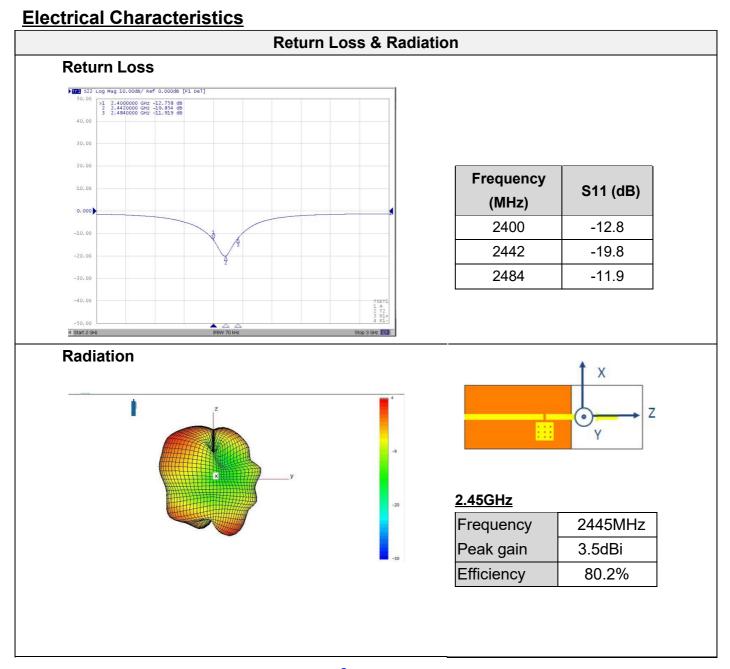
No.	Terminal Name
1	Feeding
2	Soldering

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Evaluation Board Reference





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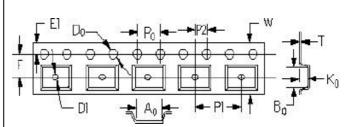
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Taping Specifications

Reel

Checking note	Index	Spec (mm)
Internal diameter of reel	Α	60.20 £ 0.50
External diameter of reel	В	178 ±1.00

Quantity/per reel	3000 pcs	
	Plastic	
Tape material	(embossed)	



Taping Blister Tape

Checking note	Index	Spec (mm)
Sprocket hole	D0	1.50 +0.10/-0.00
Distance sprocket hole to outside	E1	1.75 ± 0.10
Distance sprocket hole to pocket	F	5.50 ± 0.05
Distance sprocket hole to sprocket hole	P0	4.00 ± 0.10
Distance pocket to pocket	P1	4.00 ± 0.10
Distance sprocket hole to pocket	P2	2.00 ± 0.05
Tape width	W	12.00 +0.30/-0.10
Pocket width nominal clearance	A0	2.28 £0.13
Pocket length nominal clearance	В0	5.70 £0.13
Pocket depth minimum clearance	K0	1.58 £ 0.10
Thickness of tape	Т	0.23 £ 0.02

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Reliability Table

Test Item	Procedure	Requirements Ceramic Type	Remark (Reference)
Electrical Characterization		Fulfill the electrical specification	User Spec.
Thermal 1. Preconditioning: 50 ± 10 °C / 1 hr , then keep for 24 ± 1 hrs at room temp. 2. Initial measure: Spec: refer Initialspec. 3. Rapid change of temperature test: -30 °C to +85 °C; 100 cycles; 15 minutes at Lower category temperature; 15 minutes at Upper category temperature.		No Visible Damage. Fulfill the electrical specification.	MIL-STD-202 107
Temperature Cycling	 Initial measure: Spec: refer Initialspec. 100 Cycles (-30°C to +85°C), Soak Mode=1 (2 Cycle/hours). Measurement at 24 ± 2Hours after test condition. 	No Visible Damage. Fulfill the electrical specification.	JESD22 JA104
High Temperature Exposure	1. Initial measure: Spec: refer Initialspec. 2. Unpowered; 500hours @ T=+85℃. 3. Measurement at 24 ±2 hours after test.	No Visible Damage. Fulfill the electrical specification.	MIL-STD-202 108
Low Temperature Storage	1. Initial measure: Spec: refer Initialspec. 2. Unpowered: 500hours @ T=-30℃. 3. Measurement at 24 ±2 hours after test.	No Visible Damage. Fulfill the electrical specification.	MIL-STD-202 108
Solderability (SMD Bottom Side)	Dipping method: a. Temperature: 235 ± 5°C b. Dipping time: 3 ± 0.5s	The solder should cover over 95% of the critical area of bottom side.	IEC 60384-21/22 4.10
Soldering Heat Resistance (RSH) Preheating temperature: 150 ± 10°C. Preheating time: 1~2 min. Solder temperature: 260 ± 5°C. Dipping time: 5 ± 0.5s		No Visible Damage.	IEC 60384-21/22 4.10
Vibration	5g's for 20 min., 12 cycles each of 3 orientations Note: Use 8"X5" PCB .031" thick 7 secure points on, one long side and 2 secure points at corners of opposite sides. Parts mounted within 2" from any secure point. Test from 10-2000 Hz	No Visible Damage.	MIL-STD-202 Method 204
Mechanical Shock Three shocks in each direction shall be applied along the three mutually perpendicular axes of the test specimen (18 shocks) Peak value: 1,500g's Duration: 0.5ms Velocity change: 15.4 ft/s Waveform: Half-sine		No Visible Damage.	MIL-STD-202 Method 213
Humidity 1. Humidity: 85% R.H., Temperature: 85 ± 2 °C. 2. Time: 500 ± 24 hours. 3. Measurement at 24 ± 2hrs after test condition.		No Visible Damage. Fulfill the electrical specification.	MIL-STD-202 Method 106

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Board Flex (SMD)	1. Mounting method: IR-Reflow. PCB Size (L:100 × W:40 ×T:1.6mm) 2. Apply the load in direction of the arrow until bending reaches 2 mm. Support Solder Chip Printed crout board before teaching 45-2 Probe to evert bending force Probe to evert bending force Probe to evert bending force	No Visible Damage.	AEC-Q200 005
Adhesion	Force of 1.8Kg for 60 seconds. radius 0,5 mm DUT wide thickness shear force	No Visible Damage Magnification of 20X or greater may be employed for inspection of the mechanical integrity of the device body terminals and body/terminal junction.	AEC-Q200 006
Physical Dimension	Any applicable method using x10 magnification, micrometers, calipers, gauges, contour projectors, or other measuring equipment, capable of determining the actual specimen dimensions.	In accordance with specification.	JESD22 JB100

Revision History

Revision	Date	Content
1	2019/7/20	New issue

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